

#### WMM7040DTFN0

# Top port digital silicon Microphone

### **Descriptions**

WMM7040DTFN0 is a Silicon Microphone with digital output and top inlet for sound input. It consists of a MEMS sensor and an encoder IC. It converts sensor analog output signal into 1-bit digital PDM data. The digital output format eliminates AC coupling capacitor, reduces RF noise coupling and eases PCB layout requirement.

WMM7040DTFN0 is a cost-effective alternative to traditional electret condenser microphone (ECM). Provided on tap-and-reel, it is ideally suited for high volume applications and it can be processed directly to customer's PCB using standard automatic pick-and-place equipment and surface mounted via standard solder reflow equipment.

WMM7040DTFN0 can be used to implement the array microphones. Speech quality can be significantly improved by combining two microphones.

The WMM7040DTFN0 is manufactured in a compact 4.00mm\*3.00mm\*1.00mm, 8-pin package.

## **Features**

- PDM Output
- High SNR
- Multiple performance modes
- Ultra-Stable Performance
- Standard SMD Reflow
- RoHS/Halogen free compliant
- Omnidirectional

### **Applications**

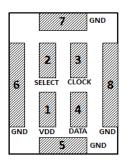
- Smart phonesSmart speakers
- Portable communication device
- Notebook and desktop
- Digital still cameras
- Portable music recorders

#### Http//:www.willsemi.com





#### **Product appearance**



#### Pin configuration (Bottom view)



Marking (Top view)

Y = Year code

WW = Week code

X X X

X X= Batch code

#### Order information

Device	Package(mm)	Shipping
WMM7040DTFN0-8/TR	4.00*3.00*1.00	5000/Reel&Tape



# **Absolute maximum ratings**

Parameter	Conditions	Min	Тур	Max	Unit
Supply voltage	VDD to GND	-0.3	-	6.5	V
	L/R,CLOCK,DATA Voltage to GND	-0.4	-	VDD+0.4V	V
Operating Temperature		-40	-	+85	$^{\circ}\mathbb{C}$
Starage Temperature	Solder on PCB	-40	-	+125	$^{\circ}\mathbb{C}$
Storage Temperature	In Tape and Reel	-10	-	+50	$^{\circ}\!\mathbb{C}$

Stresses exceeding these "Absolute Maximum Ratings" could cause permanent damage to the microphone. These are stress rating only. Functional operation at these or any other conditions beyond those indicated under "Absolute and Electrical Characteristics" is not implied. Exposure beyond those indicated under "Acoustic and Electrical Characteristics" for extended periods may affect microphone reliability.



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# **ACOUSTIC & ELECTRICAL SPECIFICATIONS**

TEST CONDITIONS:  $23 \pm 2^{\circ}$ C,  $55 \pm 20\%$  R.H., VDD=1.8V, Fclock=2.048MHz, Duty Cycle=50%, SELECT pin grounded, no load, unless otherwise indicated.

Parameter		Symbol	Conditions	Min	Тур	Max	Units
Supply Voltage		$V_{DD}$		1.6	-	3.6	V
	Supply Current		Normal operation, Fclk(1MHz~4.8MHz)	-	640	-	uA
Supply (			Low power mode, Fclk(350kHz~800KHz)	-	300	-	uA
		I <sub>sleep</sub>	Sleep mode, Fclk(<250KHz)	-	42	-	uA
	Sleep mode			0	-	250	KHz
Clock	Low power mode			350	-	800	KHz
Frequency Rang	Standard Performance Mode			1	ı	4.8	MHz
Sensi	tivity	Sense	94dB SPL @1KHz	-27	-26	-25	dBFS
Signal to N	oise Ratio	SNR	Normal mode 94dB SPL @1KHz, A-weighted	-	61	-	dB(A)
Total Harmon	ic Distortion	THD	94dB SPL @1KHz, S=Typ	-	0.15	-	%
Acoustic Overload Point		AOP	10%THD @1KHz, S=Typ	-	120	-	dB SPL
Power Suppl	y Rejection	PSR+N	100 mVpp square wave @ 217Hz, A-weighted	-	-85	-	dBFS(A)
Power Suppl Rat	-	PSRR	200 mVpp sinewave @ 1 kHz	-	65	-	dBv/FS
DC Ou	ıtput	ZOUT	DC fullscale=±100	-	1	-	%FS
Direct	tivity				Omnid	lirectional	
Data F	ormat				1/2 Cycl	e 1 bit PDM	
Logic Inp	out High	Vih		0.65x V <sub>DD</sub>	-	VDD+0 .3	V
Logic Inp	out Low	Vil		-0.3	-	0.35x VDD	V
Logic Out	put High	Voh		VDD- 0.45	-	-	V
Logic Out	put Low	Vol		-	-	0.45	V
Output Load		Cload		-	-	140	pF
Short Circuit O	Short Circuit Output Current		94dB SPL @1KHz	1		20	mA
Clock Du	Clock Duty Cycle			40		60	%
Clock Rise,	/Fall Time	TEDGE		-	-	(是理	原数5

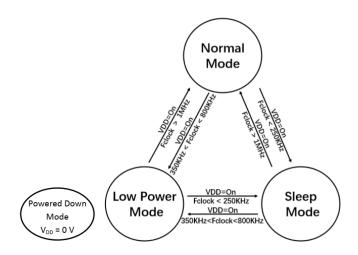
<sup>1. 100%</sup> tested.

<sup>2.</sup> IDD varies with CLOAD according to:  $\Delta$ IDD = 0.5\*VDD\* $\Delta$ CLOAD\*FCLOCK.

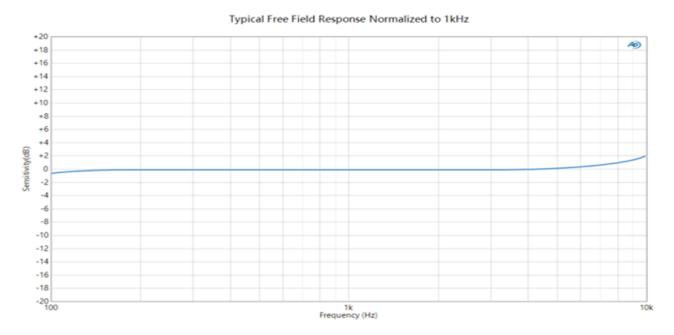


- 3. Maximum specifications are measured at maximum VDD. Typical specifications are measured at standard test Conditions .
- 4. Valid microphones states are: Power Down Mode (mic off), Low Power Mode (mic clock speed), Sleep Mode (low current, DATA = high-Z, fast startup), and Normal Mode (normal operation).
- 5. Time from FCLOCK <250 kHz to ISLEEP specification is met when transitioning from Normal Mode to Sleep Mode.
- 6. Time from FCLOCK  $\geqslant$  1 MHz to all applicable specifications are met when transitioning from Sleep Mode to Normal Mode.

## MICROPHONE STATE DIAGRAM

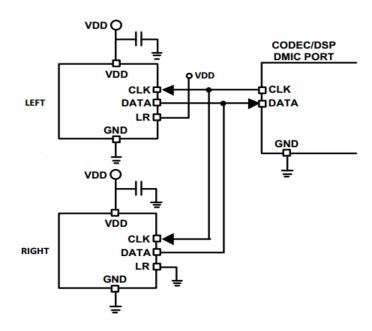


# Frequency response curve





# **Application informations**



Microphone	SELECT	Asserts DATA On	Latch DATA On
Mic (High)	$V_{DD}$	Rising Clock Edge	Falling Clock Edge
Mic (Low)	GND	Falling Clock Edge	Rising Clock Edge

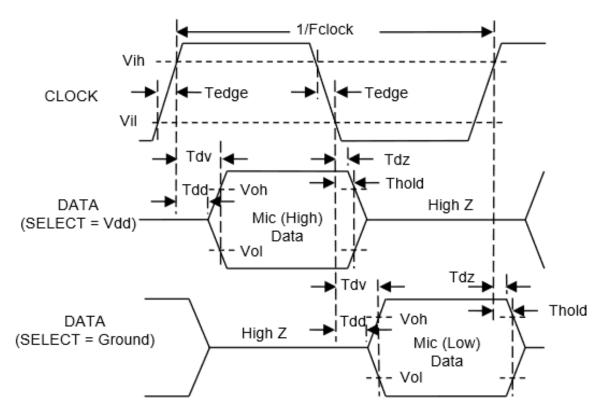
#### Note:

- All GND pins must be connected to ground.
- Capacitors near the microphone should not contain Class 2 dielectrics.





# **Clock Timing Diagram**



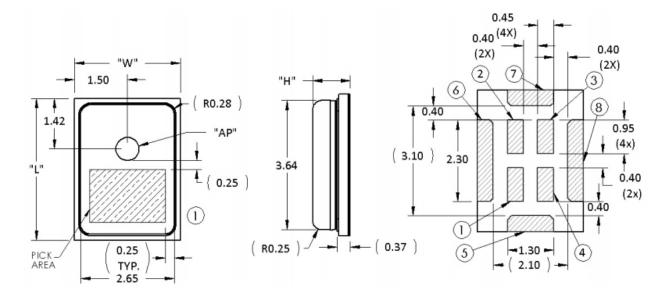
# **Timing Characteristics**

Parameter	Symbol	Min	Тур	Max	Unit	Comments
Low to High Threshold	VI-h	0.65*VDD		VDD+0.3	V	
High to Low Threshold	Vh-l	-0.3		0.35*VDD	V	
DATA into Hi Z Time	Tdz	0		20	ns	RL=1MΩ, CL=12pF
DATA Valid Time	Tdv	24	36	48	ns	RL=1MΩ,CL=12pF
Clock Jitter				0.5	ns	Period jitter in RMS
Clock Duty Cycle		40	50	60	%	
Clock Frequency		350	2400	4800	KHZ	





# **MECHANICAL SPECIFICATIONS**



Item	Dimension	Tolerance
Length(L)	4.00	±0.10
Width(W)	3.00	±0.10
Height(H)	1.00	±0.10
Acoustic Port (AP)	Ø0.65	±0.05

Pin#	Pin Name	Description	
1	VDD	Power Supply	
2	SELECT	Lo/Hi (L/R) Select	
2	SELECT	This pin is internally pulled low	
3	CLOCK	Clock input	
4	DATA PDM Output		
5	GND GND		
6	6 GND GND		
7	GND	GND GND	
8	GND	GND GND	

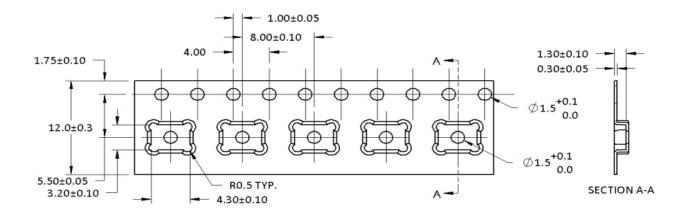
#### Notes:

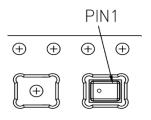
- Dimensions are in millimeters unless otherwise specified.
- Tolerance is ±0.10mm unless otherwise specified.
- Pick Area only extends to 0.25 mm of any edge or hole unless otherwise specified.
- Suggestion to use the same date code microphone in one array microphone module.





# **PACKAGING & MARKING DETAIL**





Model Number	Reel Diameter	Quantity Per Reel
WMM7040DTFN0	13"	5,000

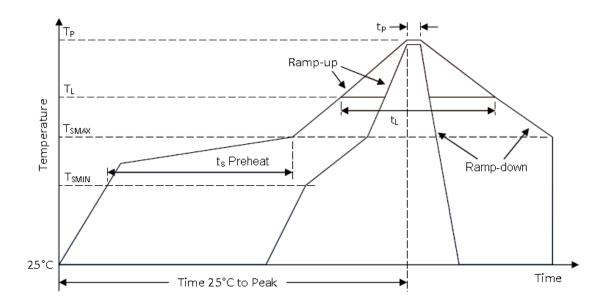
# Notes:

- Dimensions are in millimeters unless otherwise specified.
- Vacuum pickup only in the pick area indicated in Mechanical Specifications.
- Tape & reel per EIA-481.
- Labels applied directly to reel and external package.





# **REFERENCED REFLOW PROFILE**



Profile Feature	Pb-Free
Average Ramp-up rate (Tsmax to Tp)	3°C/second max.
Preheat  • Temperature Min (Tsmin)  • Temperature Max (Tsmax)  • Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-180 seconds
Time maintained above:  • Temperature (TL)  • Time (tL)	217°C 60-150 seconds
Peak Temperature (T <sub>P</sub> )	260°C
Time within 5°C of actual Peak Temperature (t <sub>P</sub> )	20-40 seconds
Ramp-down rate (TP to TSMAX)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max

### Note:

All temperatures refer to topside of the package, measured on the package body surface.



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## **ADDITIONAL NOTES**

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
  - Do not board wash or clean after the reflow process.
  - Do not brush board with or without solvents after the reflow process.
  - Do not directly expose to ultrasonic processing, welding, or cleaning.
  - Do not insert any object in port hole of device at any time.
  - Do not apply over 30 psi of air pressure into the port hole.
  - Do not pull a vacuum over port hole of the microphone.
  - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

## MATERIALS STATEMENT

Meets the requirements of the European RoHS and Halogen-Free.

## **RELIABILITY SPECIFICATIONS**

Test	Description
Thermal Shock	100 cycles air-to-air thermal shock from -40°C to +125°C with 15 minute soaks. (IEC 68-2-4)
High Temperature Storage	1000 hours at +105°C environment. (IEC 68-2-2 Test Ba)
Low Temperature Storage	1000 hours at -40°C environment. (IEC 68-2-2 Test Aa)
High Temperature Bias	1000 hours at +105°C under bias. (IEC 68-2-2 Test Ba)
Low Temperature Bias	1000 hours at -40°C under bias. (IEC 68-2-2 Test Aa)
Temperature / Humidity Bias	1000 hours at +85°C /85% R.H. under bias. (JESD22-A101A-B)
Vibration	4 cycles of 20 to 2,000 Hz sinusoidal sweep with 20g peak acceleration lasting 12 minutes in X, Y, and Z directions. (Mil-Std-883E, method 2007.2 A)
ESD-HBM	3 discharges of ±3.5kV direct contact to I/O pins. (ESD STM5.2)
ESD-LID/GND	3 discharges of ±8 kV direct contact to lid while unit is grounded. (IEC 61000-4-2)
ESD-MM	3 discharges of ±200V direct contact to I/O pins. (ESD STM5.2)
Reflow	5 reflow cycles with peak temperature of +260°C.
Mechanical Shock	3 pulses of 10000g in the X, Y, and Z direction. (IEC 68-2-27, Test Ea)
Drop Test  To be no interference in operation after dropped to marble or 1.0cm 18 times from 1.5 meter height.	
Salt mist	(50 ± 5)g/L, pH is 6.5 to 7.2, with 96 hours.( GB/T 2423.17-2008) (note 2)

#### Note:

1. After reliability tests are performed, the sensitivity of the microphones shall not deviate more than 3 dB from its initial value. (The measurement to be done after 2 hours of conditioning at 20±2 °C, R.H.60% 70%)

2. The salt mist do not evaluate performance.